

### COMMON MODE CHOKE

#### •FEATURE

- Capable of handling the highest current(up to 5A) of any chip-type common mode filter
- 2. Noise is greatly suppressed.



#### APPLICATION

 Used for power line noise suppression for any electronic devices. Used to counter adapter/battery line noise for relatively large electronic devices such as notebook, stand-alone word processor, etc.



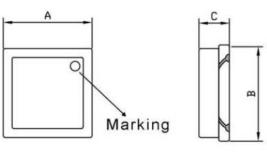
#### ORDERING INFORMATION

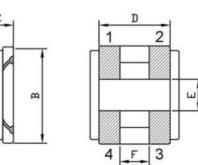
CMH0502F -251

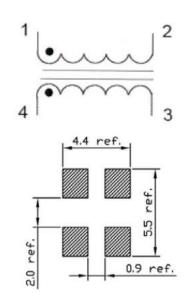
PN Impedance( $\Omega$ )

### •SHAPE AND DIMENSION CMH0502F

### •SCHEMATICS AND LAND PATTERNS(mm)





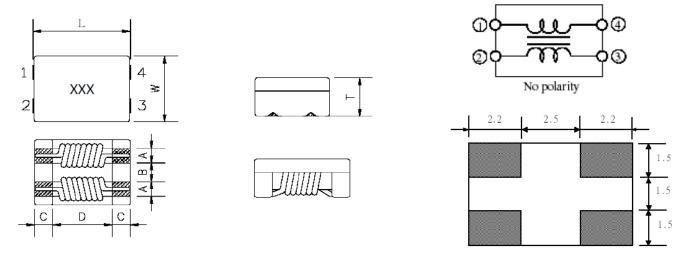


A=4.80±0.30 mm; B=5.00±0.30 mm; C=2.50 mm Max (do not include solder); D=3.50 mm Ref.

E=2.20 mm Ref.; F=1.10 mm Ref.

# COMMON MODE CHOKE CMH

#### CMH7060F



 $L=7.30\pm0.30\;mm\;;\;W=6.00\pm0.20\;mm\;;\;T=3.80\;mm\;Max\;;\;A=1.50\;mm\;Ref.\;;\;B=1.5$ 

C=1.70 mm Ref.; D=3.50 mm Ref.

#### •ELECTRICAL CHARACTEISTICS

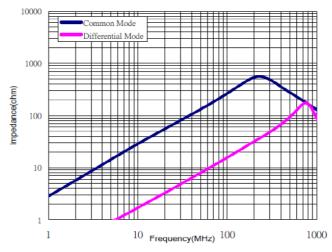
TYPE	Common mode Impedance Z(Ω) at 100MHz Typical	DC Resistance (mΩ)	Rated Current(A)	Rated Voltage(V)	Insulation Resistance (MΩ)Min
CMH0502F-251	250	14±40%	5.0	50	10
CMH0502F-501	500	19±40%	4.0	50	10
CMH0502F-102	1000	24±40%	2.5	50	10
CMH0502F-142	1400	40±40%	2.0	50	10
CMH7060F-301	300	10Max	5.0	80	10
CMH7060F-701	700	15Max	4.0	80	10
CMH7060F-102	1000	17Max	3.0	80	10
CMH7060F-132	1300	21Max	2.5	80	10

Note1: Measurement ambient temperature of Impedance, DCR and IDC : at  $25^{\circ}$ C

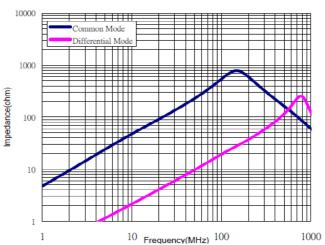
### COMMON MODE CHOKE

#### • CHARACTERISTICS

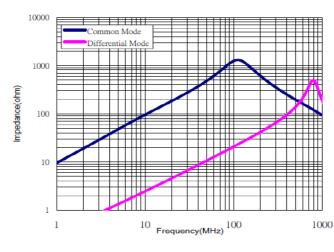
#### 1. CMH0502F-251



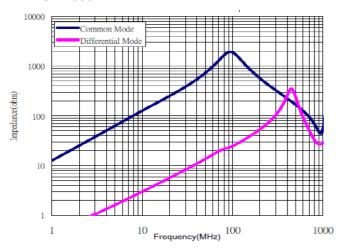
#### 2. CMH0502F-501



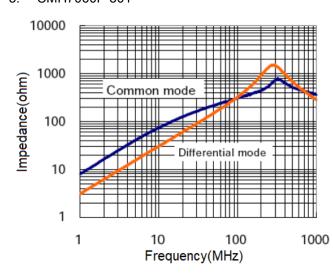
#### 3. CMH0502F-102



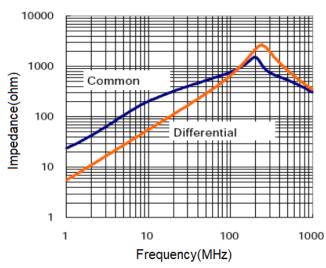
#### 4. CMH0502F-142



#### 5. CMH7060F-301

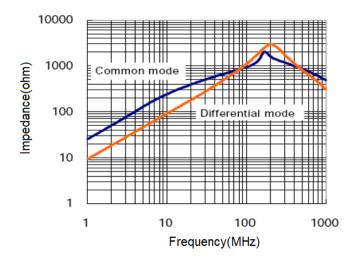


#### 6. CM7H060F-701



# COMMON MODE CHOKE CMH

#### 7. CMH7060F-102



### COMMON MODE CHOKE

#### •GENERAL CHARACTERISTICS

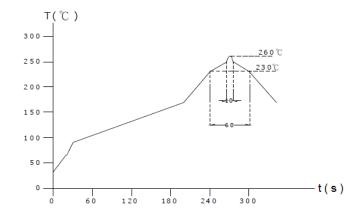
- 1. Operating temperature range: -40 TO + 105°C (Includes temperature when the coil is heated)
- 2. External appearance: On visual inspection, the coil has no external defects.
- Terminal strength: After soldering. Between copper plate and terminals of coil.
   Push in two directions of X.Y withstanding at below conditions.
   Terminal should not peel off. (refer to figure at right)
  - Applied force: 5N; Duration: 60sec.
- 4. Insulating resistance: Over  $100M\Omega$  at 100V D.C. between coil and core.
- 5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
- 6. Temperature characteristics: Inductance coefficient (0~2,000)x10-6/°C (-25~+80°C degree Celsius) Inductance deviation within±5.0%, after 96 hours
- 7. Humidity characteristics (Moisture Resistance): Inductance deviation within ±5%, after 96 hours in 90~95% relative humidity at 40 ±2°C and 1 hour drying under normal condition.
- 8. Vibration resistance: Inductance deviation within ±5%, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10Hz) with 1.5mm P-P amplitudes.
- 9. Shock resistance: Inductance deviation within ±5%, after being dropped once with 981m/s² (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
- 10. Resistance to Soldering Heat: 260°C, 10 seconds. (See attached recommend reflow)
- 11. Storage environment:

Storage condition: Temperature Range: 0°C ~ 35°C ; -40°C ~ 105°C (after PCB)

Humidity Range: 50% ~ 70% RH

12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use. Reflow profile recommend:

#### Lead - free heat endurance test



#### Lead-free the recommended reflow condition

